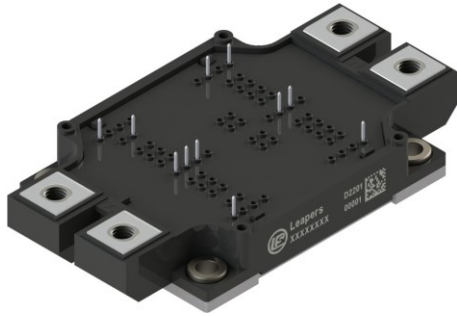


### Description

The DFS270HF12I3C2 is a Half Bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips designed for the applications such as Motor drives and Renewable energy.



### Features

- 1200V/7.0mΩ
- Low thermal resistance with Si<sub>3</sub>N<sub>4</sub> AMB
- 175°C maximum junction temperature
- Low inductive design
- Thermistor inside
- Pressfit terminal
- Copper base size: 79mm\*62mm

### Applications

- xEV Applications
- Motor Drive
- Vehicle Fast Chargers
- Renewable energy

### Circuit diagram

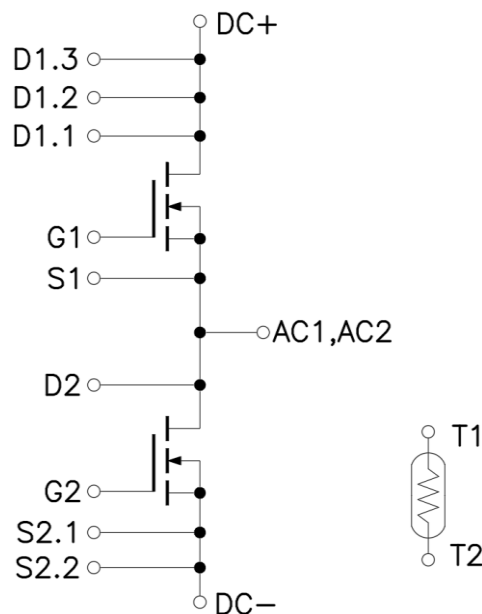


Figure 1. Out drawing & circuit diagram for DFS270HF12I3C2

## Pin Configuration and Marking Information

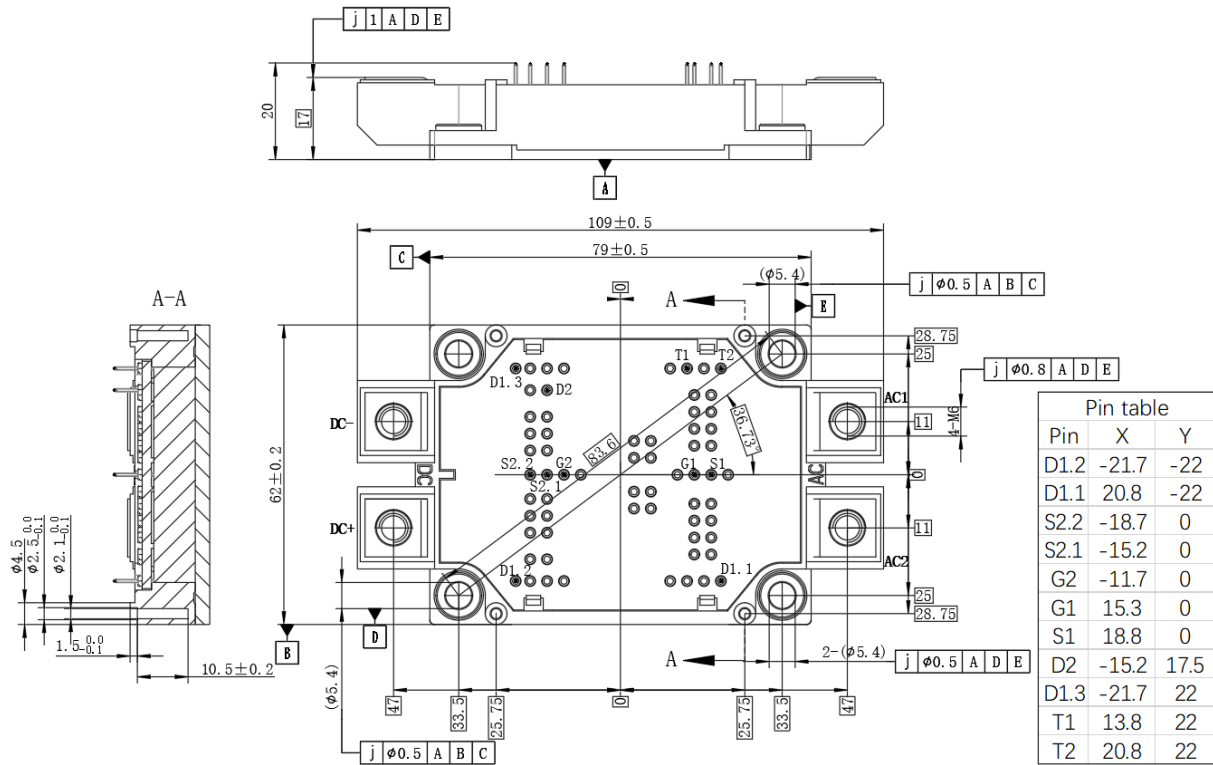


Figure 2. Pin configuration

## Module

| Parameter                                | Conditions                                   | Value      | Unit |
|------------------------------------------|----------------------------------------------|------------|------|
| Isolation Voltage                        | RMS, f =50Hz, t =1min                        | 3.4        | KV   |
| Material of module baseplate             | -                                            | Cu         | -    |
| Creepage distance                        | terminal to heatsink<br>terminal to terminal | 14.5<br>10 | mm   |
| Clearance                                | terminal to heatsink<br>terminal to terminal | 12.5<br>10 | mm   |
| CTI                                      | -                                            | >400       | -    |
| Module lead resistance, terminals – chip | T <sub>C</sub> =25°C                         | 0.3        | mΩ   |
| Mounting torque for module mounting      | M5, M6                                       | 3 to 6     | Nm   |
| Weight                                   | -                                            | 250        | g    |

### Maximum Ratings ( $T_j = 25^\circ\text{C}$ unless otherwise specified)

| Symbol     | Parameter                      | Conditions                                                                  | Ratings    | Unit             |
|------------|--------------------------------|-----------------------------------------------------------------------------|------------|------------------|
| $V_{DS}$   | Drain-Source Voltage           | G-S Short                                                                   | 1200       | V                |
| $V_{GS}$   | Gate-Source Voltage            | D-S Short, AC frequency $\geq 1\text{Hz}$ , Note1                           | -10 to 20  | V                |
| $I_{DS}$   | DC Continuous Drain Current    | $T = 25^\circ\text{C}$ , $V_{GS} = +15\text{V}$                             | 279        | A                |
| $I_{DS}$   | DC Continuous Drain Current    | $T_C = 65^\circ\text{C}$ , $V_{GS} = +15\text{V}$                           | 240        | A                |
| $I_{SD}$   | Source (Body diode) Current    | $T_C = 25^\circ\text{C}$ , with ON signal                                   | 279        | A                |
| $I_{SD}$   | Source (Body diode) Current    | $T_C = 65^\circ\text{C}$ , with ON signal                                   | 240        | A                |
| $I_{DSM}$  | Pulse Drain Current            | $T_C = 65^\circ\text{C}$ , Pulse width = 1ms, $V_{GS} = 18\text{V}$ , Note2 | 600        | A                |
| $P_{tot}$  | Total Power Dissipation        | $T_C = 25^\circ\text{C}$                                                    | 790        | W                |
| $T_{jmax}$ | Max Junction Temperature       | -                                                                           | 175        | $^\circ\text{C}$ |
| $T_{jop}$  | Operating junction Temperature | -                                                                           | -40 to 150 | $^\circ\text{C}$ |
| $T_{stg}$  | Storage Temperature            | -                                                                           | -40 to 125 | $^\circ\text{C}$ |

Note1: Recommended Operating Value, +15V/-5V, +15V/-4V

Note2: Pulse width limited by maximum junction temperature

### NTC characteristics

| Symbol       | Parameter              | Condition                                                      | Value |      |      | Unit             |
|--------------|------------------------|----------------------------------------------------------------|-------|------|------|------------------|
|              |                        |                                                                | Min.  | Typ. | Max. |                  |
| $R_{25}$     | Resistance             | $T_c = 25^\circ\text{C}$                                       | -     | 5    | -    | $\text{k}\Omega$ |
| $\Delta R/R$ | Deviation of $R_{100}$ | $T_c = 100^\circ\text{C}$ , $R_{100} = 493\Omega$              | 5     | -    | 5    | %                |
| $P_{25}$     | Power dissipation      | $T_c = 25^\circ\text{C}$                                       | -     | -    | 20   | mW               |
| $B_{25/50}$  | B-value                | $R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$  | -     | 3375 | -    | K                |
| $B_{25/80}$  | B-value                | $R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$  | -     | 3411 | -    | K                |
| $B_{25/100}$ | B-value                | $R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$ | -     | 3433 | -    | K                |

### MOSFET Electrical characteristics (T<sub>j</sub>=25°C unless otherwise specified, chip)

| Symbol                        | Item                            | Condition                                                                                                                                  |                       | Value |       |      | Unit |
|-------------------------------|---------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------|-----------------------|-------|-------|------|------|
|                               |                                 |                                                                                                                                            |                       | Min.  | Typ.  | Max  |      |
| V <sub>(BR)DSS</sub>          | Drain-Source Breakdown Voltage  | V <sub>GS</sub> =0V, I <sub>D</sub> =300uA                                                                                                 |                       | 1200  | -     | -    | V    |
| I <sub>DSS</sub>              | Zero gate voltage drain Current | V <sub>DS</sub> =1200V, V <sub>GS</sub> =0V                                                                                                |                       | -     | 3     | -    | μA   |
| V <sub>GS(th)</sub>           | Gate-source threshold Voltage   | I <sub>D</sub> =105mA, V <sub>DS</sub> =V <sub>GS</sub>                                                                                    | T <sub>j</sub> =25°C  | 1.8   | 2.7   | -    | V    |
| I <sub>GSS</sub>              | Gate-Source Leakage Current     | V <sub>GS</sub> =20V, V <sub>DS</sub> =0V                                                                                                  | T <sub>j</sub> =25°C  | -     | -     | 400  | nA   |
| R <sub>DS(on)</sub><br>(Chip) | Static drain-source             | I <sub>D</sub> =270A                                                                                                                       | T <sub>j</sub> =25°C  | -     | 7.0   | 9.1  | mΩ   |
|                               | On-state resistance             | V <sub>GS</sub> =15V                                                                                                                       | T <sub>j</sub> =175°C | -     | 10.2  | -    | mΩ   |
| V <sub>DS(on)</sub><br>(Chip) | Static drain-source             | I <sub>D</sub> =270A                                                                                                                       | T <sub>j</sub> =25°C  | -     | 1.89  | 2.46 | V    |
|                               | On-state Voltage                | V <sub>GS</sub> =15V                                                                                                                       | T <sub>j</sub> =175°C | -     | 2.75  | -    | V    |
| C <sub>iss</sub>              | Input Capacitance               | V <sub>D</sub> =850V, V <sub>GS</sub> =0V, f =100KHz                                                                                       |                       | -     | 8.7   | -    | nF   |
| C <sub>oss</sub>              | Output Capacitance              |                                                                                                                                            |                       | -     | 2.64  | -    | nF   |
| C <sub>rss</sub>              | Reverse transfer Capacitance    |                                                                                                                                            |                       | -     | 0.021 | -    | nF   |
| Q <sub>g</sub>                | Total gate charge               | V <sub>DD</sub> =850V, I <sub>D</sub> =180A, V <sub>GS</sub> =+15/-5V                                                                      |                       | -     | 540   | -    | nC   |
| t <sub>d(on)</sub>            | Turn-on delay time              | V <sub>DD</sub> =600V<br>I <sub>D</sub> =270A<br>V <sub>GS</sub> =+15/-4V<br>R <sub>G</sub> =3.3Ω<br>Inductive load<br>switching operation | T <sub>j</sub> =25°C  | -     | 41    | -    | ns   |
|                               |                                 |                                                                                                                                            | T <sub>j</sub> =150°C | -     | 39    | -    |      |
| t <sub>r</sub>                | Rise time                       |                                                                                                                                            | T <sub>j</sub> =25°C  | -     | 23    | -    | ns   |
|                               |                                 |                                                                                                                                            | T <sub>j</sub> =150°C | -     | 18    | -    |      |
| t <sub>d(off)</sub>           | Turn-off delay time             |                                                                                                                                            | T <sub>j</sub> =25°C  | -     | 109   | -    | ns   |
|                               |                                 |                                                                                                                                            | T <sub>j</sub> =150°C | -     | 117   | -    |      |
| t <sub>f</sub>                | Fall time                       |                                                                                                                                            | T <sub>j</sub> =25°C  | -     | 13    | -    | ns   |
|                               |                                 |                                                                                                                                            | T <sub>j</sub> =150°C | -     | 37    | -    |      |
| E <sub>on</sub>               | Turn-on power dissipation       |                                                                                                                                            | T <sub>j</sub> =25°C  | -     | 6.21  | -    | mJ   |
|                               |                                 |                                                                                                                                            | T <sub>j</sub> =150°C | -     | 6.33  | -    |      |
| E <sub>off</sub>              | Turn-off power dissipation      |                                                                                                                                            | T <sub>j</sub> =25°C  | -     | 4.31  | -    | mJ   |
|                               |                                 |                                                                                                                                            | T <sub>j</sub> =150°C | -     | 5.62  | -    |      |
| R <sub>th(j-c)</sub>          | FET Thermal Resistance          | Junction to Case                                                                                                                           |                       | -     | 0.19  | -    | K/W  |
| R <sub>th(c-f)</sub>          | Contact thermal Resistance      | With thermal conductive grease, Note3                                                                                                      |                       | -     | 0.015 | -    | K/W  |

Note3: Assumes Thermal Conductivity of grease is 0.9W/m·K and thickness is 50μm.

### Body Diode Electrical characteristics (T<sub>j</sub>=25°C unless otherwise specified, chip)

| Symbol          | Item                              | Condition                                        |                       | Value |      |     | Unit |
|-----------------|-----------------------------------|--------------------------------------------------|-----------------------|-------|------|-----|------|
|                 |                                   |                                                  |                       | Min.  | Typ. | Max |      |
| V <sub>SD</sub> | Body Diode Forward Voltage        | V <sub>GS</sub> =-5V<br>I <sub>SD</sub> =270A    | T <sub>j</sub> =25°C  | -     | 4.9  | -   | V    |
|                 |                                   |                                                  | T <sub>j</sub> =175°C | -     | 4.2  | -   |      |
| T <sub>rr</sub> | Reverse recovery time             | V <sub>DD</sub> =600V<br>I <sub>D</sub> =270A    | T <sub>j</sub> =25°C  | -     | 24   | -   | ns   |
|                 |                                   |                                                  | T <sub>j</sub> =150°C | -     | 47   | -   |      |
| Q <sub>rr</sub> | Reverse recovery charge           | V <sub>GS</sub> =+15/-4V<br>R <sub>G</sub> =3.3Ω | T <sub>j</sub> =25°C  | -     | 1.1  | -   | μC   |
|                 |                                   |                                                  | T <sub>j</sub> =150°C | -     | 4.7  | -   |      |
| E <sub>rr</sub> | Diode switching power dissipation | Inductive load<br>switching operation            | T <sub>j</sub> =25°C  | -     | 0.63 | -   | mJ   |
|                 |                                   |                                                  | T <sub>j</sub> =150°C | -     | 2.74 | -   |      |

### Test Conditions

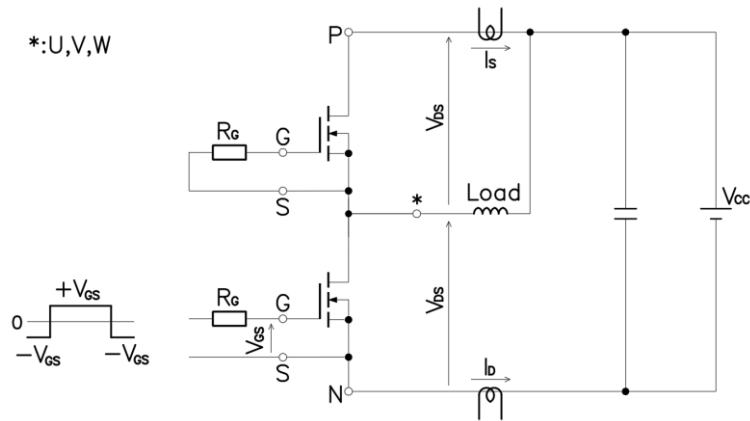


Figure 3. Switching time measure circuit

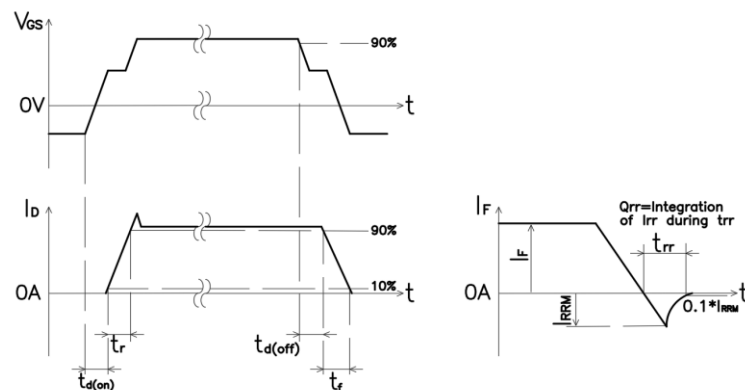


Figure 4. Switching time definition

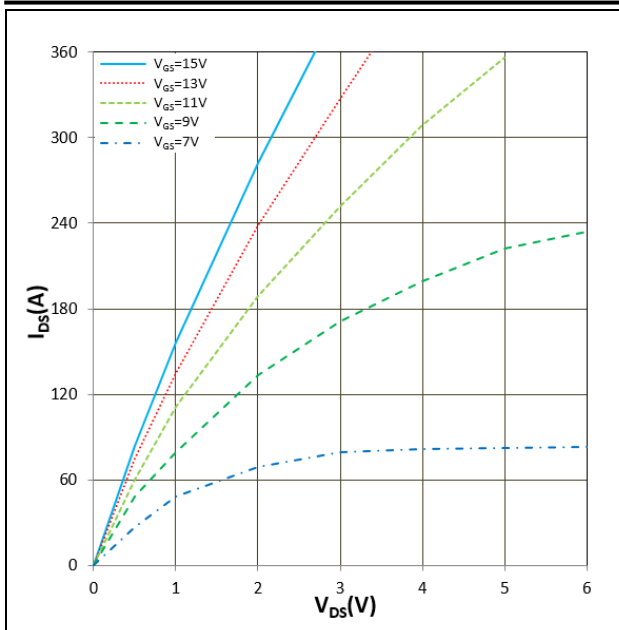


Figure 5.  $I_{DS}$  vs  $V_{DS}$   
 $T_j = 25^\circ\text{C}$

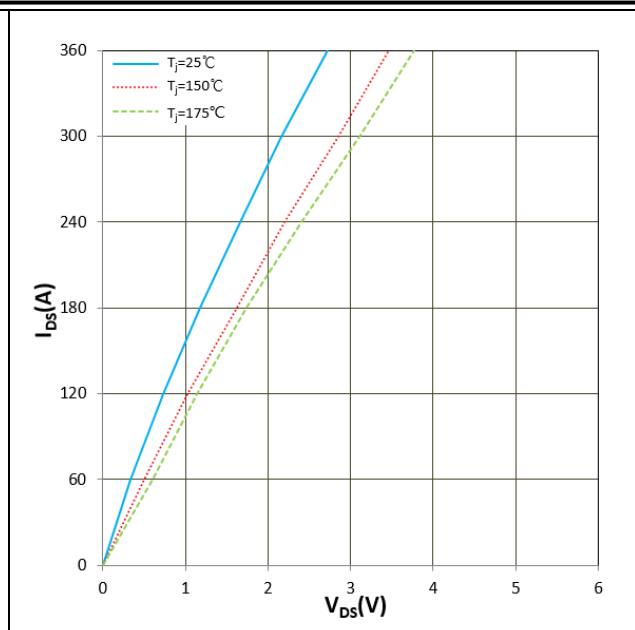


Figure 6.  $I_{DS}$  vs  $V_{DS}$   
 $V_{GS} = +15\text{V}$

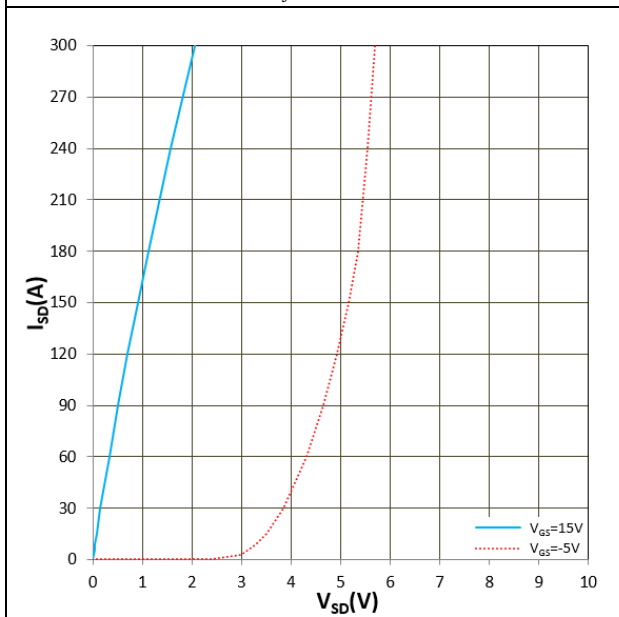


Figure 7.  $I_{SD}$  vs  $V_{SD} (V_F)$   
 $T_j = 25^\circ\text{C}$

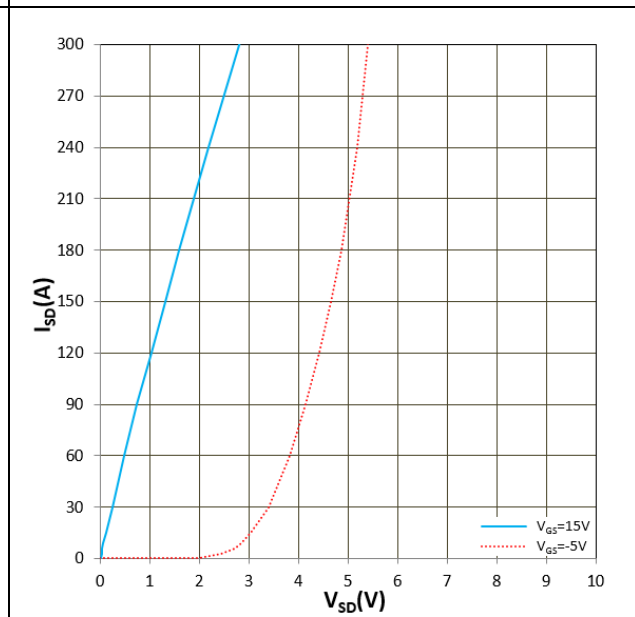


Figure 8.  $I_{SD}$  vs  $V_{SD} (V_F)$   
 $T_j = 175^\circ\text{C}$

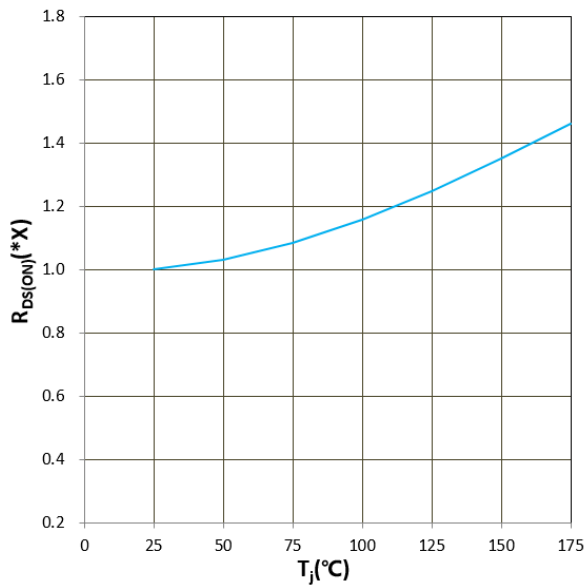


Figure 9.  $R_{DS(ON)}$  vs  $T_j$   
 $V_{GS} = +15\text{V}$ ,  $I_D = 270\text{A}$ ,  $1.0X = 7.0\text{m}\Omega$

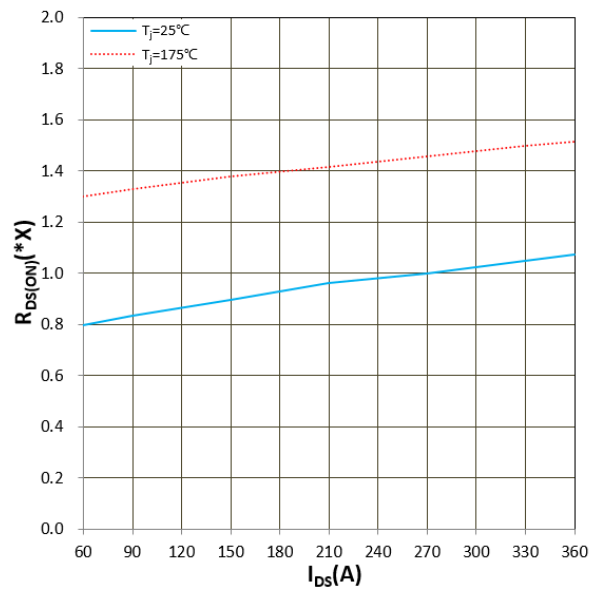


Figure 10.  $R_{DS(ON)}$  vs  $I_{DS}$   
 $V_{GS} = +15\text{V}$ ,  $I_D = 270\text{A}$ ,  $1.0X = 7.0\text{m}\Omega$

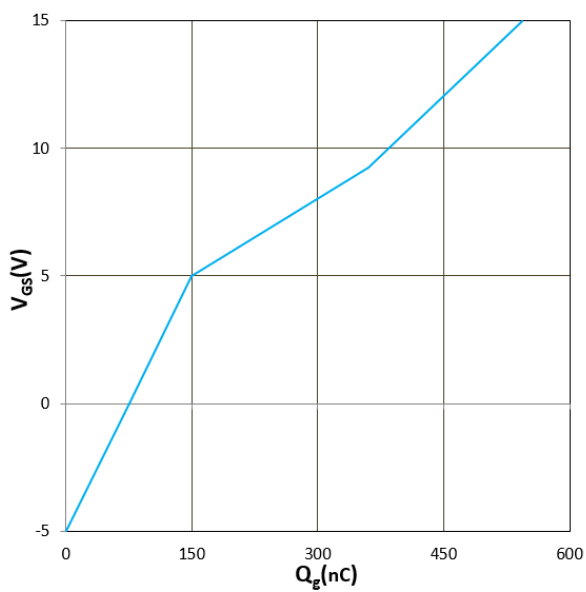


Figure 11.  $V_{GS}$  vs  $Q_g$   
 $V_{DS} = 800\text{V}$ ,  $I_D = 180\text{A}$ ,  $T_j = 25^{\circ}\text{C}$

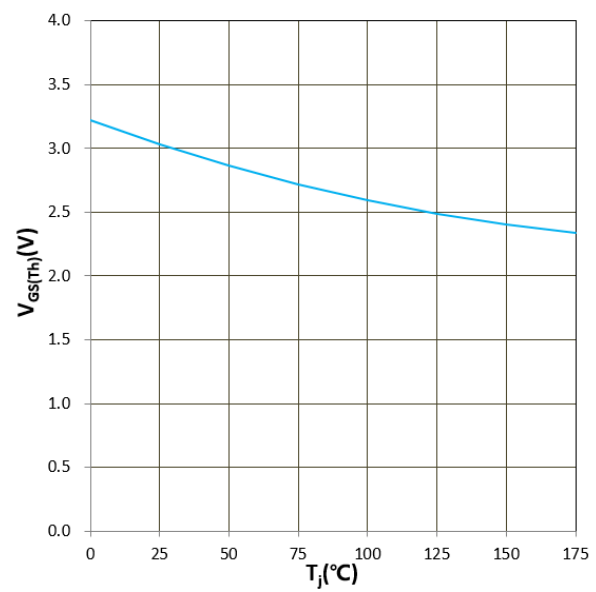


Figure 12.  $V_{GS(TH)}$  vs  $T_j$   
 $V_{GS} = V_{DS}$ ,  $I_D = 105\text{mA}$

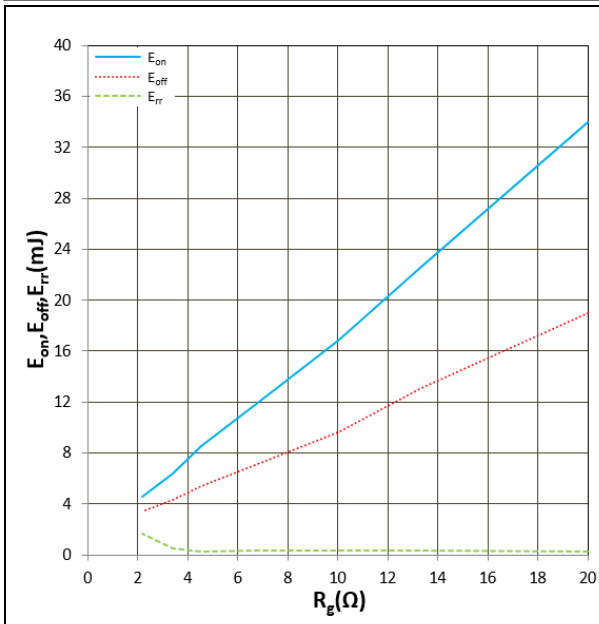


Figure 13.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $R_g$   
 $T_j = 25^\circ\text{C}$ ,  $V_{CC} = 600\text{V}$ ,  $V_{GS} = +15\text{V}/-4\text{V}$ ,  $I_D = 270\text{A}$   
 Inductive Load

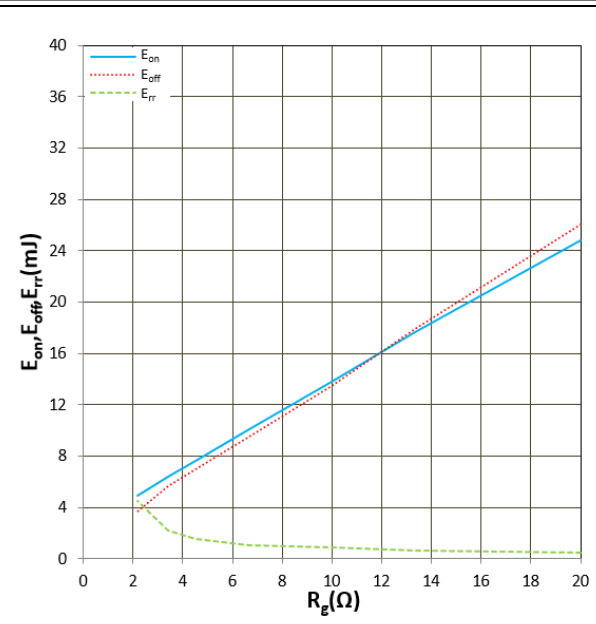


Figure 14.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $R_g$   
 $T_j = 150^\circ\text{C}$ ,  $V_{CC} = 600\text{V}$ ,  $V_{GS} = +15\text{V}/-4\text{V}$ ,  $I_D = 270\text{A}$   
 Inductive Load

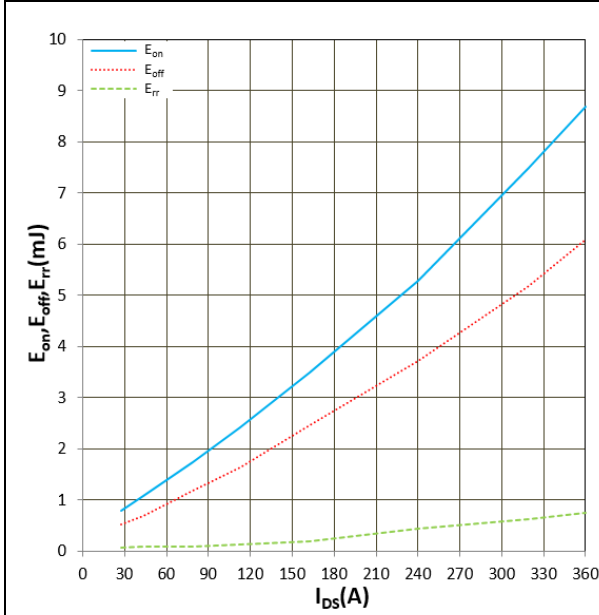


Figure 15.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $I_{DS}$   
 $T_j = 25^\circ\text{C}$ ,  $V_{CC} = 600\text{V}$ ,  $V_{GS} = +15\text{V}/-4\text{V}$ ,  $R_g = 3.3\Omega$   
 Inductive Load

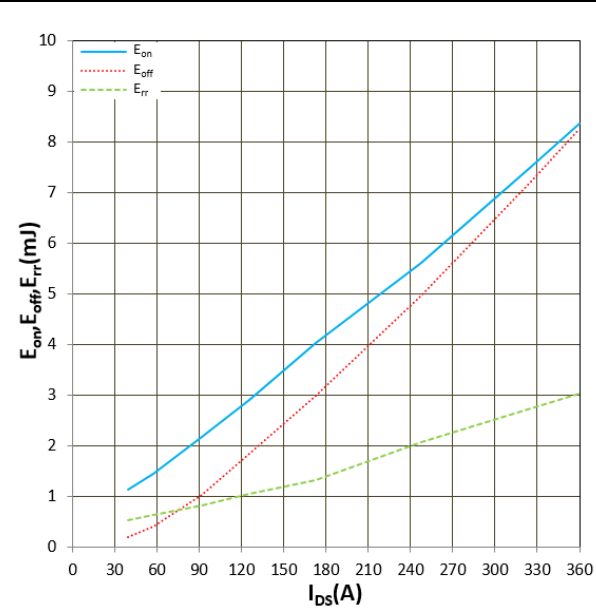


Figure 16.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $I_{DS}$   
 $T_j = 150^\circ\text{C}$ ,  $V_{CC} = 600\text{V}$ ,  $V_{GS} = +15\text{V}/-4\text{V}$ ,  $R_g = 3.3\Omega$   
 Inductive Load



### IMPORTANT NOTICE:

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